

T5321 Series

T5421 Series

5 x 7 mm Surface Mount High Reliability

Tristate/Non-Tristate, 1MHz to 100MHz

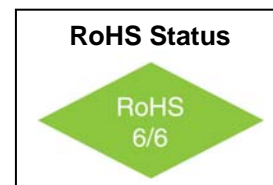


Features

- Leadless chip carrier package is hermetically sealed for superior aging and field performance
- Crystal angle controlled to ± 1 minute for excellent temperature stability
- 168 hour Class B burn-in and extensive environmental testing for best performance in rugged field environments
- Start-up time <10 ms, typical
- Tristate option available
- Calculated MTBF is 3.8×10^6 hours at 125°C

Application

- Surface Mounted PCB projects requiring high reliability CMOS clock waveforms



Description

These high reliability oscillators provide HCMOS clock waveforms for applications subjected to the most stringent environmental conditions. They are mechanically robust and weigh less than 0.2 grams. This 5x7mm SMD package has a hermetic seal, thus ensuring the integrity of each oscillator. Each oscillator is burned-in at 125°C for 168 hours, temperature cycled and centrifuged then fully tested in accordance with Table 1. Reliability tests are performed per Table 2. The calculated MTBF is 3.8×10^6 at 125°C.

Electrical Specifications

| Parameter | Symbol | Condition | Min | Typ | Max | Unit | Note |
|-----------------------------|-----------------|---|---|------------|--------------------|------|-----------|
| Frequency Range | F | | 1 | | 100 | MHz | |
| Frequency Stability | $\Delta F/F$ | Vs. Operating Temperature | ± 25 | | ± 75 | ppm | See Chart |
| | | Aging 1 st Year After 1 st Year | | | ± 3 ± 1 | | |
| Operating Temperature Range | T | | -55° | | +125° | °C | See Chart |
| Input Voltage | V _{cc} | | 3.00 | 3.30 | 3.6 | V | |
| Input Current | I _{cc} | | | | 16 | mA | |
| Waveform Symmetry | | Measured at 50% V _{DD} | 40/60 | 45/55 | 60/40 | % | |
| Rise / Fall Time | Tr/Tf | CMOS, 15pF, 20% to 80% (<60MHz) 20% to 80% (≥60MHz) | | 3.0 2.0 | 4.0 2.5 | ns | |
| | | CMOS, 30pF, 20% to 80% (<60MHz) 20% to 80% (≥60MHz) | | 4.0 3.0 | 5.0 4.5 | | |
| Output Level | "Zero" Level | Sinking 16mA | | | 0.4 | V | |
| | "One" Level | Sourcing 8mA | V _{DD} -0.4 | | | | |
| Input requirement for pin.1 | | Output enable - Output disable (Tristate) | pin 1 may float or 2.8V min (sourcing 400 uA) pin 1 requires 0.4V max (sinking 400 uA) | | | | |



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Environmental and Mechanical Conditions

| Parameter | Condition |
|------------------------|---|
| Shock | 1000 Gs, 0.35 ms, ½ sine wave, 3 shocks in each plane |
| Vibration | 10-2000 Hz of .06" d.a. or 20Gs, whichever is less |
| Humidity | Resistant to 85° R.H. at 85°C |
| Leak | Per MIL-STD-883, Method 1014, Cond. A1 and C1 |
| Case | Hermetically sealed ceramic LCC |
| Pads | 40 microinch of gold over nickel |
| Resistance to Solvents | Per MIL-STD-202, Method 215 |
| Marking | Epoxy ink or laser engraved |

| FIXED OUTPUT | TRISTATE | Operating Temperature | Frequency Stability |
|--------------|----------|-----------------------|---------------------|
| Model | Model | | |
| T5321 | T5421 | -55°C to +85°C | ±25 ppm |
| T5322 | T5422 | -55°C to +85°C | ±50 ppm |
| T5323 | T5423 | -55°C to +125°C | ±75 ppm |
| T5324 | T5424 | -55°C to +125°C | ±50 ppm |

Table 1

Each unit undergoes the following:

- | | |
|--|--|
| 1. Stabilization Bake | MIL-STD-883 Method 1008, Cond., B |
| 2. Temperature Cycling | MIL-STD-883 Method 1010, Cond, B |
| 3. Constant Acceleration | MIL-STD-883 Method 2001, Cond, A |
| 4. Burn-in | MIL-STD-883 Method 1015, Cond B (125°C for 168 hours with bias) |
| 5. Fine Leak | MIL-STD-883 Method 1014, Cond. A1 |
| 6. Gross Leak | MIL-STD-883 Method 1014, Cond C |
| 7. Electrical Test at 25°C and temperature extremes, as follows: | |
| A. Frequency | F. Duty Cycle |
| B. Current | G. Frequency at 3.65V |
| C. Rise Time | H. Frequency at 3.0V |
| D. Fall Time | I. "Zero" logic level |
| E. Duty Cycle | J. "One" logic level |
| K. Tristate | |

Test Data on each unit is available for additional cost

Thermal Characteristics

Thermal Resistance

From Junction to Case, R_{θjc} 16 °C/Watt

Surface Mount Application

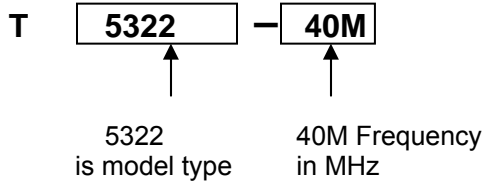
These packages are designed for reflow soldering in accordance with recommended profiles. For hand-soldering, the temperature of the iron should not exceed 400°C for three seconds.



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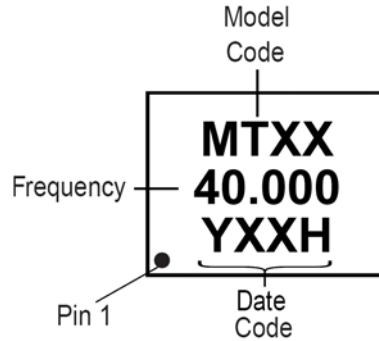


How to Order

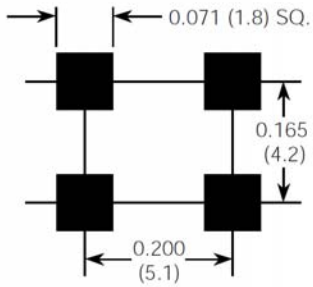


Marking Specification

The format for the marking is:

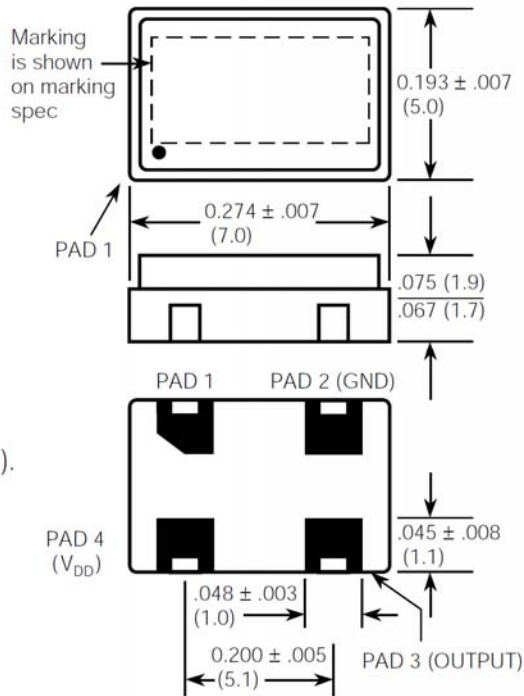


Package



SUGGESTED PC PADS

Millimeters are shown in ().



| Pin # | T5321-5324 | T5421-T5424 |
|-------|------------------------|------------------------|
| Pin 1 | Not Connected | Tristate |
| Pin 2 | Ground | Ground |
| Pin 3 | Output | Output |
| Pin 4 | +3.3V, V _{DD} | +3.3V, V _{DD} |



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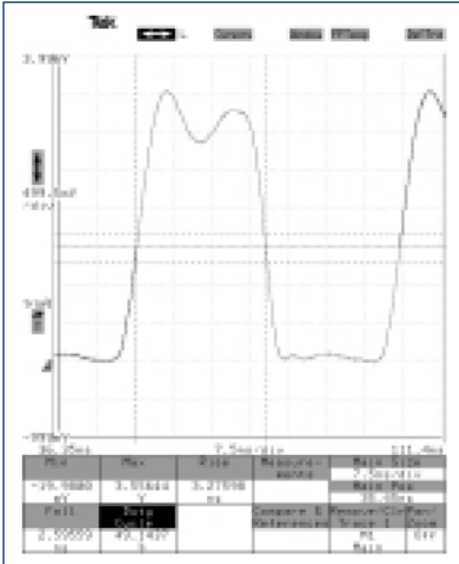


Fig.1 T5322-20M with 25pf load

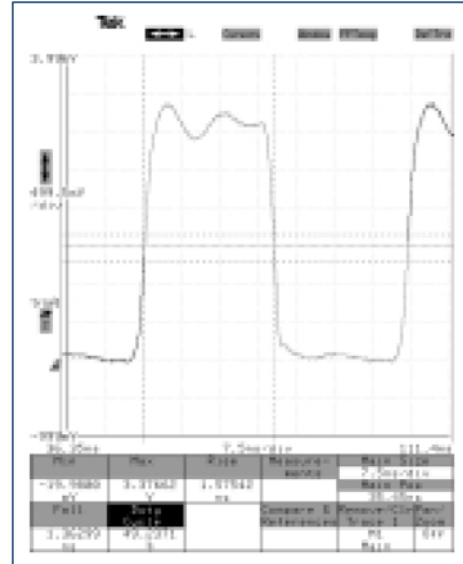
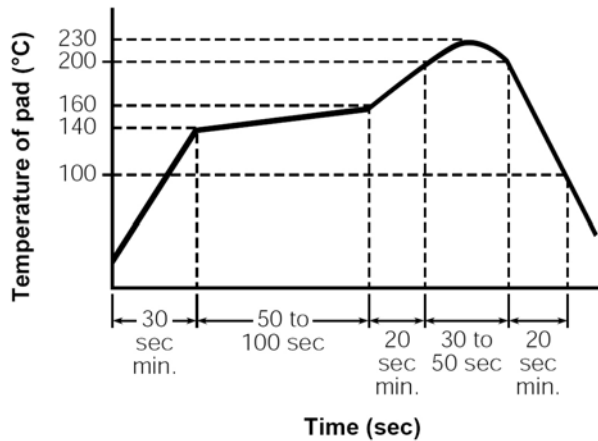
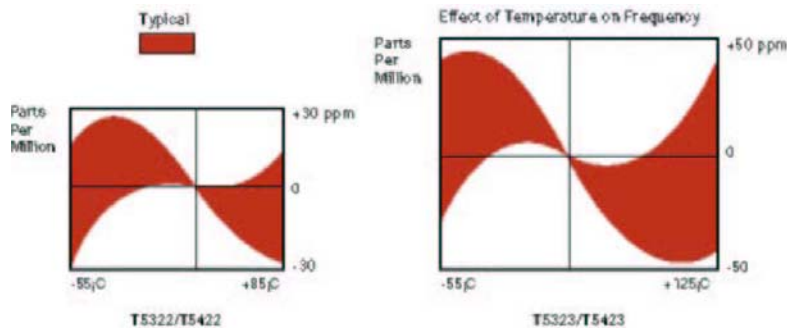


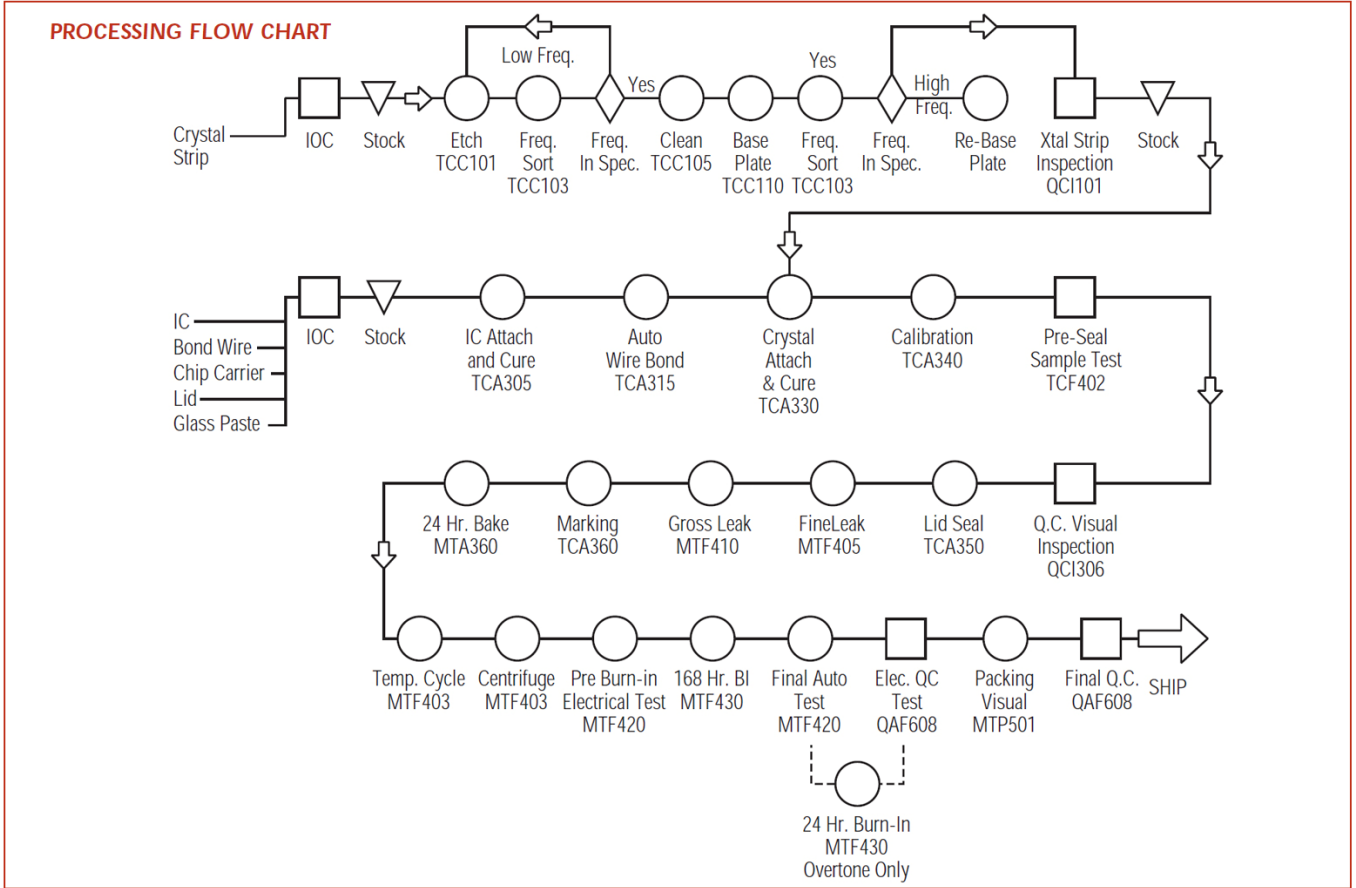
Fig.2 T5322-20M without load



Recommended Reflow Soldering Profile



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TABLE 2
Reliability Test Procedures and Conditions for Quartz Crystal Oscillators

1. Group A

Electrical Characteristics at -55°C, 25°C and 125°C
 (85°C for T5322 and T5422)
 Frequency @ 3.0, 3.3 and 3.6 volts
 Symmetry (Duty Cycle)
 Input current
 Zero/One levels
 Rise/Fall times
 Physical Dimensions
 Length/width
 Height
 Package finish (Corrosion, discoloration, etc.)
 Marking placement/legibility

2. Group B- Life Test

1000 hrs at or above 125°C, 3.3V VDC, with proper load

3. Group C- All units have passed Group A testing

A. Subgroup 1-8 pcs.

| <u>Standard</u> | <u>Condition</u> | <u>Description</u> | <u>End Point Measurement</u> |
|-----------------|-------------------------|---|------------------------------|
| MIL-STD-883 | Method 2002 COND.B | Mechanical Shock 1500 g's, 0.5ms 5 drops, 6 axis | Frequency Output waveform |
| MIL-STD-883 | Method 2007 COND. A. | Vibration, var. freq. 20 g's, 0.06" disp., 20- 20, 000-20 Hz | Frequency Output waveform |
| MIL-STD-883 | Method 2003 | Solderability | Visual 95% Coverage |

B. Subgroup 2-4 pcs (One-half of Subgroup 1)

| <u>Standard</u> | <u>Condition</u> | <u>Description</u> | <u>End point Measurement</u> |
|-----------------|------------------------|---|------------------------------|
| MIL-STD-883 | Method 1011 COND. B | Thermal Shock Liq. To liq. -55°C to 125°C, 15cycles | Frequency Output waveform |
| MIL-STD-202 | Method 105 COND. B | Altitude, 3.44 inch Hg. 12 hrs | Frequency Output waveform |
| MIL-STD-883 | Method 1004 | Moisture resist. with 3.3V applied 25°C to 65°C, 90 to 100% RH, 10 cycles | Frequency Output waveform |
| MIL-STD-202 | Method 210 COND.A | Resistance to Solder Heat Immersion @350°C 3.5 sec | Frequency Output waveform |

C. Subgroups 3-4 pcs. (One half of Subgroup 1)

| <u>Standard</u> | <u>Condition</u> | <u>Description</u> | <u>End point Measurement</u> |
|-----------------|---------------------------|--|--|
| | Storage Temp. No. Oper | 24 hrs. @ -55°C 24 hrs. @ 125°C | Frequency Output waveform |
| MIL-STD-883 | Method 1009 COND. A | Salt Atmosphere 24 hrs. @ 35°C 0.5-3.0% Solution | Frequency Output waveform Visual |
| MIL-STD-883 | Method 1014 COND. A1 | Fine Leak | Qs <5 X10 ⁻⁸ |
| MIL-STD-883 | Method 1014 COND. C1 | Gross Leak | Visual in 125°C Detector fluid |

